

Greetings!

History has been developed continuously for the happiness of mankind. While people enjoy better life with all those developments, we now face a bigger challenge to protect and preserve the environment for tomorrow.

With a leading edge technology based on the atmospheric plasma solution, APP has joined this effort by producing better products which consume less energy and require shorter process time.

APP is a total plasma solution provider encompassing all the technologies from Ar, N2 to Air plasma serving various customer needs. Through functional treatments like reduction, sterilization, nano coating, ashing and etching, APP enables our customers in display, semiconductor, automotive, Bio and solar cell industries to make their products most competitive and cost effective.

In addition to the plasma, APP also provides reliable low frequency generators and automation equipments for enhanced and optimized solutions.

Everyone at APP is fully committed to provide the best value to our customers in harmony with the environment and appreciates your unwavering support.

Banabas Xim

Thank you!

Overview

Company APP Co., Ltd **Foundation** 2006. 02. 23

TEL / E-mail +82-31-373-5956 / sales@applasma.com

Address 7-12, Dongtansandan 2-gil, Hwaseong-si, Gyeonggi-do, S.KOREA, 18487

Business Fields

Dry Surface Control

- Ar Plasma
- N2 Plasma
- Air Plasma
- Corona Plasma

Nano Etching

- A-Si
- Si3N4
- Poly-Si
- PAC
- SiO2
- MoTi
- SiON

Nano Coating

- Hydrophobic
- SiO2
- HMDS
- TEOS

Diagnostic & Automation

- OES Diagnostic System
- Robot System
- Conveyor System
- Roll to Roll System



We create value of 10 dollars from a technology of 1 dollar value.

We use 10 dollars to make it worth of 100 dollars.

1달러의 기술로 10달러의 가치를 만들고 10달러를 100달러 가치로 쓰는 회사

我们用1美元的技术,创造10美元的价值 我们使用10美元,产生100美元的效益

Global Network



2006 ~ 2008 's

2006. 02 Founded APP Co., Ltd

2006. 10 Certified venture company, Designated RIS Project by the Ministry

of Commence, Industry and Energy. (KOREA)

2007. 01 Establish laboratory effiliated company

2007. 11 Register "Hydrophobic, Super-Hydrophobic System" patent

2008. 03 Designated "Export enterprise business" in Korea

2008. 05 Certified ISO system quality

Thinking toward the Humanity
APP Co.,Ltd is professional Enterprise
in the field of atmospheric plasma R&D system

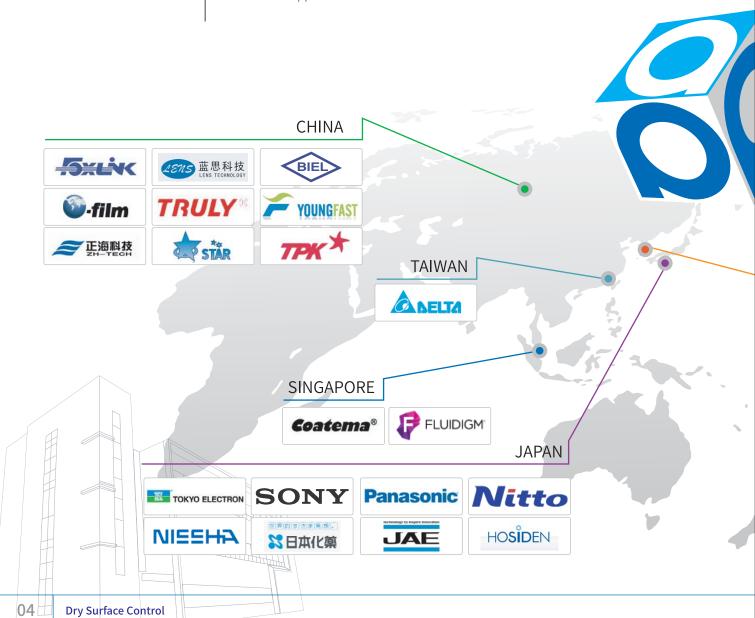
History

2009 ~ 2013's

2009. 07 Launch Atmospheric plasma equipment exports in U.S.A
 2009. 09 Application for all-round Touch panel manufacturing process
 2010. 01 Move place of business to Samsung Technopark

2010. 03 Launch Atmospheric plasma equipment in Germany

2013. 08 Application for 'Flexible' mobile Line



2014 ~ 2016's

- 2014. 01 Move place of business to Dongtan Industrial Complex
- 2014. 06 Application for AEP(Atmospheric Etching Plasma) on OLED Line
- 2015. 01 G8 Ar Direct plasma Launching (2500mm)
- 2015. 03 Build and Relocate HQ to New company Building
- 2015. 06 "PI" AP ashing system Develop
- 2016. 03 Portable plasma "PLAMI" Launching
- 2016. 03 3D N2 plasma Launching

2017 ~ 2019's

2017. 02 APP INDIA Mumbai Open2017. 10 APP USA San Jose Open

2018. 04 Launch BAM(Business As Mission)

2018. 10 Enter OLED / Semi Market

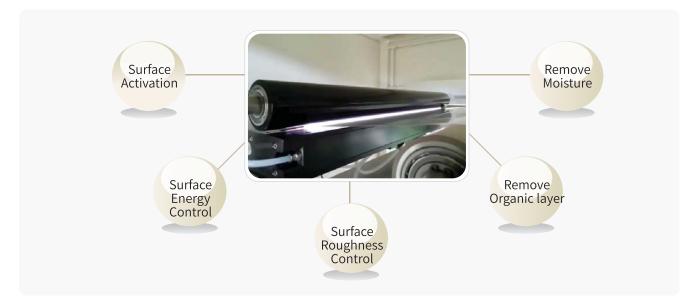
Customers



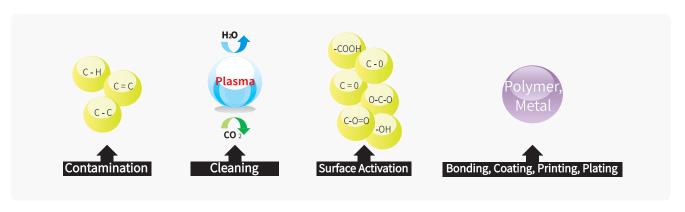
KOREA



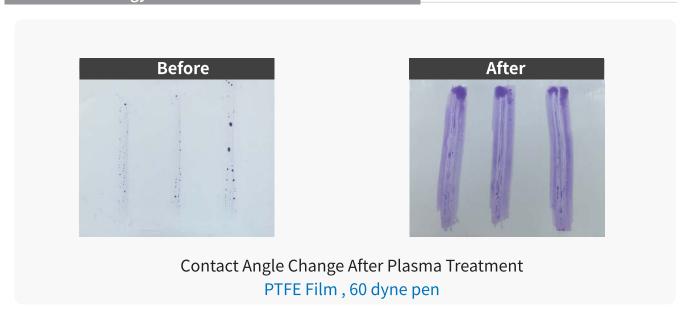
Major effects of DSC



Cleaning and Activation

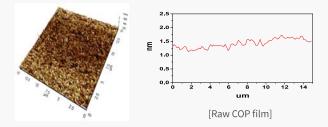


Surface Energy Control

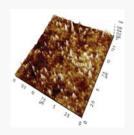


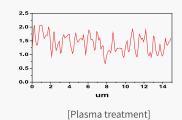
Surface Roughness Control

COP film TEST RESULT: AFM IMAGE



Туре	Raw COP film
Roughness (Ra)	0.533 \pm 0.118 nm

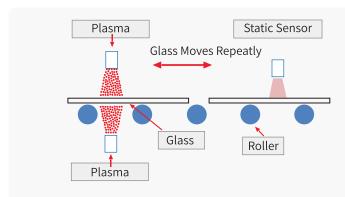


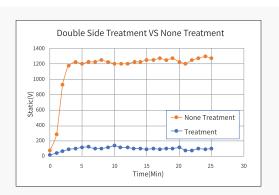


Туре	Plasma treatment
Roughness (Ra)	2.879 ± 0.372 nm

✓ Rough surface can improve adhesion property.

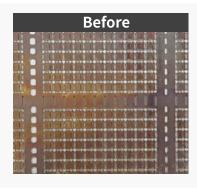
Anti Static Control

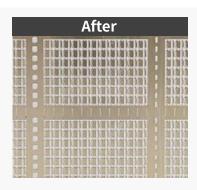




DSC Technology Makes Anti Static Surface

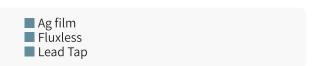
Atmospheric Reduction



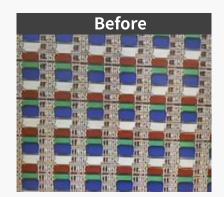


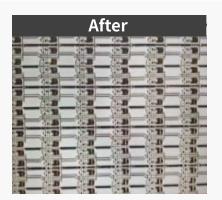
Application





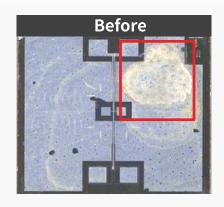
Atmospheric Ashing

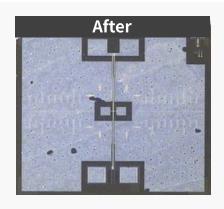




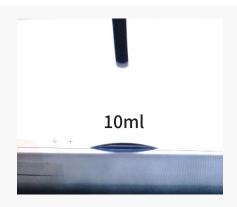
Over Coating / RGB layer removal

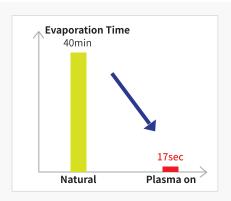
Atmospheric Ashing





Atmospheric Moisture Removal

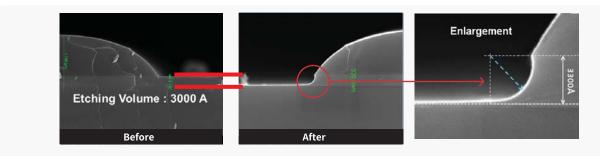




Item	Plasma ON	Plasma OFF
Drop size	10µℓ*3Point	10 <i>µl</i> ∗3Point
10μl Evaporation	17sec	40min

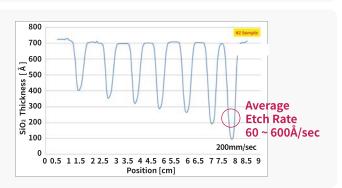
 $\frakking{\%}\ 10\mbox{ml}$ drop size can be Evaporated 100 Times Faster Than Natural Evaporation.

Atmospheric Etching

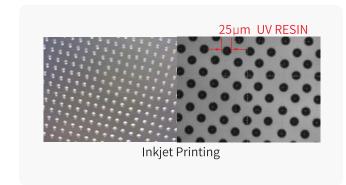


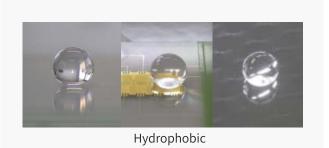
Etching

- A-Si
- poly-Si
- SiO2
- > Si/SiO2 selective etching
- SiON
- Si3N4
- PAC
- MoTi



Hydrophobic Nano Coating





SiO₂ Nano Coating

[Performance of Deposited SiO₂ Thin film]

	Hardness	refractive Index	Insulating performance	Deposition Rate	
Results	>9H	1.44	> 5.0MV/cm	~ 57Å/s	
Remarks	Pencil Hardness	at 632.8nm	Breakdown Voltage (at 448Å)	57 <i>7</i> 43	

OLED/LCD Display



Flexible OLED



TSP treatment



Automotive touch pad



3D glass

- Initial Glass Cleaning
- Buffer Layer
- TFT Cleaning before PI Layer
- Improve of Blue OLED Efficiency
- Pretreatment Seal Dispensing

- Pretreatment TAB bonding
- Moisture Removal
- PI Film Cleaning & Activation
- Etching Process
- Enhance WVTR

LED Package / LCD



LED package



LCD monitor



After plasma



No plasma

- for injection molding
- resin/leadframe adhesion
- Pretreatment for die attach
- Pretreatment for wire bonding
- for molding
- for glue removal
- TFT process: Pre-deposition, Pre-Photolithography, pre-etching
- Color filter process : Pre-deposition, Pre-Photolithography
- Cell ACF Bonding
- Module process : ACF Bonding
- Initial Cleaning
- PR Ashing
- RGB ashing
- Cleaning before BM process
- Cleaning before etch process
- Cleaning before CVD, Sputter
- Cleaning before Photo process
- Cleaning before BM & RGB process
- Cleaning before PI ink-jetting
- Cleaning before Wet etching process
- Pre Cleaning before COG bonding
- Pre-treatment for RGB Ink-jetting

Semiconductor



Pretreatment wire bonding



After plasma No plasma



Wire(Au&Cu)



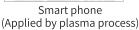
Wafer cleaning

- Wafer Cleaning
 - Initial cleaning
 - PR removal
 - Pretreatment plating
- Screen printing for die attach
- Cu wire cleaning
- Oxide layer removal
- Organic removal

- Solder Ball Cleaning
- Solder Ball MountingAu bumping
- Wire bonding (Ag, Cu)
- ACF bonding

Fexible Display / Smart Pad/PCB/FPCB







PCB treatment



PCB/FPCB



Reduction of Cu FPCB

- Before Lamination : OCA film, DAT film
 - Optical Bonding: LOCA, Super view resin
 - COG,COF bonding(ACF)
 - TAB bonding
 - Printing of Black Matrix
 - Slit coating of photoresist
 - AF spray coating
 - AR spray coating
 - Painting of phonecase
 - Dotting of spacer
 - DFR Lamination
- Residue removal of Photoresist

- Residue removal of photoresist
- Carbon removal
- Teflon activation
- Reduction of Cu oxide
- Pre treatment for DAF film laminating
- Pre treatment of PET (PI) film for electroless Cu plating

BIO



Hydrophobic coating



Bio



Skin plasma



Biochip bonding

- Petridish treatment
- Biochip bonding (PDMS, Plastic, glass)
- Pretreatment glucose dispensing
- Cell culture treatment
- Sterilization

- Hydrophilic / Hydrophobic treatment
- Hydrophilic / Hydrophobic coating
- Super hydrophilic / Super hydrophobic coating

Solar cell



Solar cell



R2R Plasma



Film



Solder ball

- $1. \ Pre-treatment \ for \ activation, \ cleaning, \ coating (AF, AG, AR) \ and \ improve \ adhesion$
- 2. APP Plasma improve adhesion of film/foil/sheet, Film/Film, Film/Glass, Film/Metal, Glass/Metal, Organic/Metal, Organic/film
- 3. APP technology is highly effective at treating for solarcell manufacture process
- Treatment material: MO, AL, Cu, Stainless steel, Glass, Film (PVCm EVA, PET, PI, PEN, ITO)

Solar Materials	APP Surface Treatment Purpose
EVA top - Glass (film)	Improve adhesion with Glass (PVC)
Glass - CIGS (CdTe)	Improve adhesion of Cdte / CiGS to glass
Aluminum foil	Clean foil for lamination
Silicon wafer(roll form)	Improve wettability for PV
Polyimide film	Improve surface wettability for metal adhesion

NEW

DSC (Dry Surface Control) for **OLED** Process



8.5G Ar Plasma (Max: 3 Meter)

OLED Process

Window Glass
Touch sensor
Encapsulation layer
RGB layer
TFT layer
Buffer layer
PI layer
Carrier glass

- ✓ Surface energy control
- ✓ PI layer control
- ✓ TFT layer control
- ✓ Anti-Static

Poly-Si Buffer layer	
PI layer	
Carrier glass	











FEATURES

- Visible Plasma
- Minimized Power Consumption
- Mounting with Robot
- None Thermal Damage

- Maximized Plasma Length
- Low Temp. Plasma
- Hand Held



PenJet SPEC.

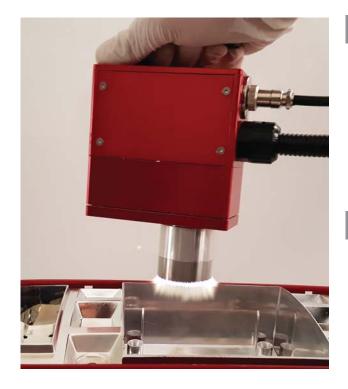
SPEC.	АРР
Power Input	220 VAC, 50/60 Hz, 10A
LF Power	100W
Frequency	20KHz
Input Gas	CDA 0.3MPA
Flow Rate	20 LPM
Head Weigth	0.6kg
Power Weigth	4kg
Plasma Length	10mm







AIR



Hand - Held Air Plasma

D 40Ø

Dimension	50 x 110 x 155
Weight	1.5kg
Cooling Type	Air
GAS	CDA
Feature	Handy type Plasma



ILT200R-40

Mounted Type Plasma

№ 80Ø

Dimension	80 x 150 x 172
Weight	2.5kg
Cooling Type	Air
GAS	CDA
Feature	80Ø size plasma
	mount with robot



Air Plasma

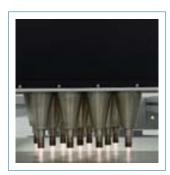




Corona



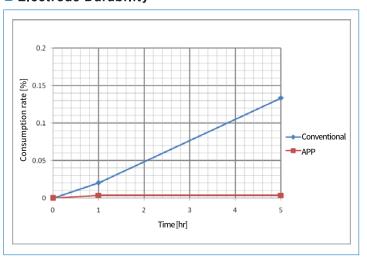
■ Multi Torch

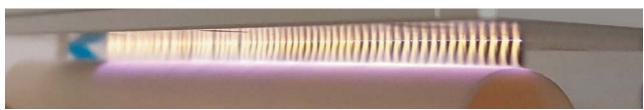


■ Comparison Of Particle Generation



■ Electrode Durability















Automotive IC chip Low temp. (by hand)

Semiconductor

FEATURES

- Visible Plasma
- Minimized N₂ Consumption

- Maximized Plasma Length
- Low Temp. Plasma



APP vs. Conventional

SPEC.	APP	Conventional
Plasma length	~ 15mm	~ 6mm
Contact angle	<5° at 10mm	< 5° at 6mm
N ₂ Consumption	30 ~ 60 lpm	100 ~ 200 lpm
Power Consumption	500W at 200mm	1KW at 200mm
Visibility	Visible	None visible

2D N₂ Plasma

2D N₂ Plasma

100/200/300/400 ~ 2500



Plasma Reactor		
Materials	Ceramic: AL203 Purity 99.97%	
Plasma Area	100mm ~ 2500 [mm]	
Cooling Type	Air / Water	

FEATURES

Arc Free Plasma

Maximized Plasma Length ~ 10G

DBD N₂ Plasma



Power Supply	
Input Voltage	220V ±10%,3phase
	50/60Hz
	(With E1 Ground)
Output Voltage	Depends on model
Output Frequency	30[KHz] Variable
Efficiency	More than 95%
Voltage Regulation	Within 5%
Communication	Rs232 or D-sub
	25pin connector



Utility Supply Unit	
N2 MFC	TSC-145 / 0~500[slm]
CDA MFC	TSC-120 / 0~3[slm]
Input Voltage	± 15 VDC or $+24$ VDC
Output Voltage	0~5[V] or 4~20[mA]
Response Time	Within 2 [sec]
Accuracy	Within \pm 0.1% of F.S
Communication	RS232 or D-sub 25pin
Materials	STS316L



Large scale (8G ~)

No Ozone/NOx! No Particle!

for Cleaning & Ashing





Industry

ILP Series ILP-200/300/350/400/500/600/700/800/1000/1200/1500

FEATURE

Plasma surface treatment by In-Line type on Atmospheric Pressure

- Cost Saving by improvement of productivity and Eco-friendly processing
- Surface Treatment on various materials like Glass, Film, PCB and LCD
- Reduction of Gas Consumption and Electricity (existing comparison 1/20~1/30)
- Eco-friendly Surface Treatment without secondary contamination



- B/M printing preprocessing
- Preprocessing of AF/AG Coating
- Preprocessing of Wet Cleaning









[ILP-400S]



[ILP-450S]







[ILP-500R]

Mounted

MD-R2R Series DRTR-650/700/800/900/1000

FEATURE

Roll to Roll Both sides treatment Film (PET, PMMA, etc) / Metal Film (Cu, Al, Sus)

APPLICATION

Flim Cleaning DFR Lamination Printing Electronics Fuel Cell process PR coating





[MDCR-300]



Mounted

MD Series

MD-60/100/150/200/250/300/400/500/600/700/800/1000/1200/1500/2200

FEATURE

Easy to install on existing Equipment like Cleaning, inspection and Lamination purpose

APPLICATION

Touch Panel Manufacturing, LCD, OLED, SEMICONDUCTOR etc









R & D

MyPL Series MyPL 100/200/300 , MyPL Auto 100/200/300

FEATURE

Plasma surface treatment on Atmospheric Pressure

- Surface modification, Activation and Cleaning

APPLICATION

Application: R&D/ Prototype manufacture

- Touch screen

- Preprocessing of Wire Bonding
- Flexible display
- ACF/COF/COG bonding
- Printing/NANO Printing









Portable

Hand plasma PLAMI

FEATURE

Hand held type plasma. Flexible RF cable 4.3m length East to demonstration



Application: R&D/ Prototype manufacture

- Touch screen
- Preprocessing of Wire Bonding
- Flexible display
- ACF/COF/COG bonding
- Printing/NANO Printing











Nano Coating & Etching

Hydrophobic Nano Coating

Hydrophobic

IHP Series IHP-1000/2000

FEATURE

Hydrophobic surface treatment on Atmospheric Pressure

- Hydrophobic NANO Coating

APPLICATION

R&D Field of functional Coating

- Bio Sensor
- Smart watch
- Micro LED
- UV Imprinting
- Optical Device
- Water proof device
- PCB/FPCB
- Light Diffuser lens
- Contact Lens



[IHP-1000]

Nano Coating / "SiO2 Nano Coating"

In-line process

IDP Series IDP-1000/2000

FEATURE

Optional NANO Coating by Processing Gas on

Atmospheric Pressure

- PMMA, SiO2, Acryl Acid

APPLICATION

R&D

- Insulator film for TFT device
- Optical film
- Carbon Fiber heater
- Micro lens
- LED Package
- Photo Mask
- RFID Device



[IDP-1000]

Etching

Etching

IEP Series

IEP-1000/2000

FEATURE

Surface Etching according to process condition on Atmospheric Pressure

APPLICATION

Etching Process on OLED, LCD, SEMICONDUCTOR

- A-Si
- Poly-Si
- SiO2
- > Si/SiO2 selective etching
- SiON
- Si3N4
- PAC
- MoTi



[IEP-1000]

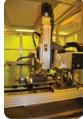
Customized Automation

Plasma Treatment Before Spray Coat: customized automation



- AF (Anti -Finger Print)
- AG (Anti-Glare)
- AR (Anti-Reflect)
- IF (Invisible Finger Print)







IEP (Inline Etching Plasma) Auto Assembling System NANO Coating System







Roller Conveyor Buffer Zone Conveyor Film Tape Attaching



Equipment/System

- Mass Production: Cleaning, Bonding, Ashing, Etching system conveyor type, R2R type, Roll Conveyor, Scan type.
- R&D: Lab scale Plasma machine same as Mass Production system.
- OES Diagnostic system

Module / System

- Easy installation for in-Line process.
- Plasma reactor & Controller (PLC/Touch , Gas Control)
- R2R (Roll to Roll) system

Customer Service

- Plasma demonstration Center
- · Various plasma test is available.







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